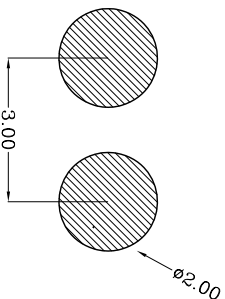
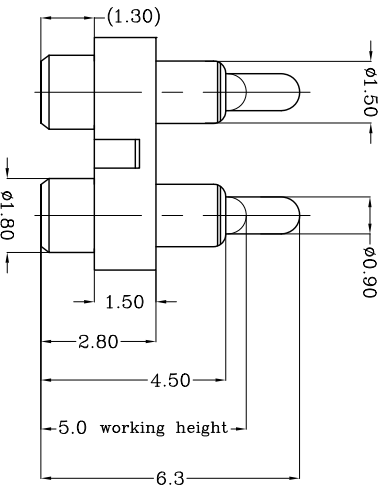
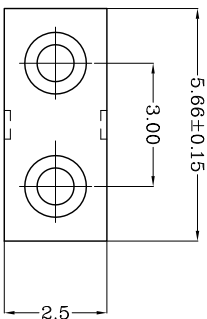
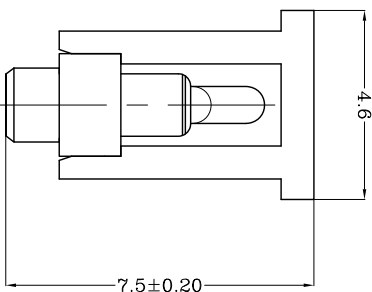
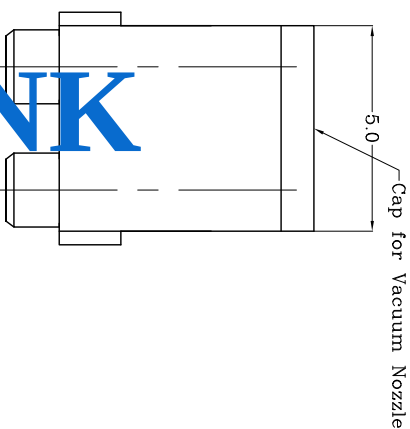
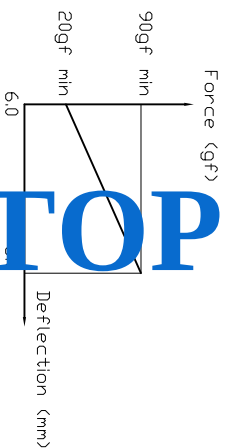


DWG NO.
C-100160



Recommended solder paste thickness is 0.10 mm
Recommended PCB Layout



USED ON

Notes:
1 Material, Housing: PA 4.6 (30% Glass Filled)

Contact: Brass

2 Mechanical demands:

Plating Plunger: Min 0.4um Au over 1.4um Ni

Plating Body: Min 0.10um Au over 1.4um Ni.

LDC		update remark	2007/09/24	ANGLE: 11	NAME BATTERY PGD CONNECTOR 2 POSITIONS			
-				SURF TEXTURE: 32/	PGC-15-6-3-R-2P-3.0PH			
DIST				REMOVE BURRS, BREAK SHARP EDGES R0.05 MAX	SCALE	A4	DWG NO.	SHEET
-		LTR REVISION RECORD	APVD	DATE	1:1		C-100160	1 OF 1
				DO NOT SCALE PRINT				REV C

DIMENSIONS IN MM TOLERANCES UNLESS OTHER SPECIFIED	MATL	HT TR	FIN
0 = ±	D/WN	APVD	—
0.0 = ±0.15	aln		
0.00 = ±0.10	REL		
0.000 = ±.0005	CHK		

Top-Link
 Electronics
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100160-2
PART NUMBER